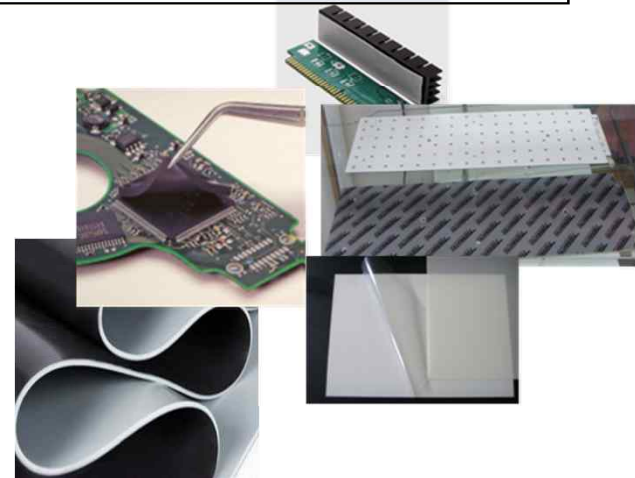




Thermal Solution

TMT-Thermal Pad Series



THERMATEC
Thermal conductive sheet Maker

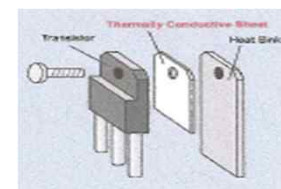
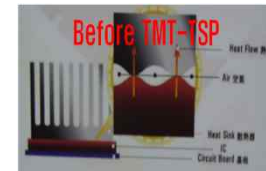
TMT-TSA Series(Thermal Silicone Pad)

are used to fill the gaps between thermal transfer surfaces, such as between microprocessors and heat-sinks, in order to increase thermal transfer efficiency.

These gaps are normally filled with air which is a very poor conductor.

KEY FEATURES

- ▶ Elimination of air gaps to reduce thermal resistance
- ▶ High conformability to reduce interfacial resistance
- ▶ Low-stress vibration dampening
- ▶ Compatible with automated dispensing equipment



| Typical Property | TMT-100 -LF01 | TEST Method |
|------------------------------|------------------|-------------|
| Color | Pink / White | Visual |
| Thickness (mm) | 6.3T ± 0.5 | ASTM D374 |
| Thermal Conductivity (W/m•k) | 1.0 | ASTM D5470 |
| Hardness(Shore 00) | 25 ± 10° | ASTM D2240 |
| Density (g/cm ³) | 2.3 | ASTM D792 |
| Dielectric Strength(KV/mm) | 24 | ASTM D149 |
| Volume Resistivity(Ω•cm) | 10 ¹⁴ | ASTM D257 |
| Continuous Temp(°C) | -40 ~ 200 | |
| Flame Rating | V-0 | UL94 |

Note

- * UL file E257359
- * ROHS pass & No Halogen free
- * Reinforcement Carrier : Glass fiber (Pink Golor)